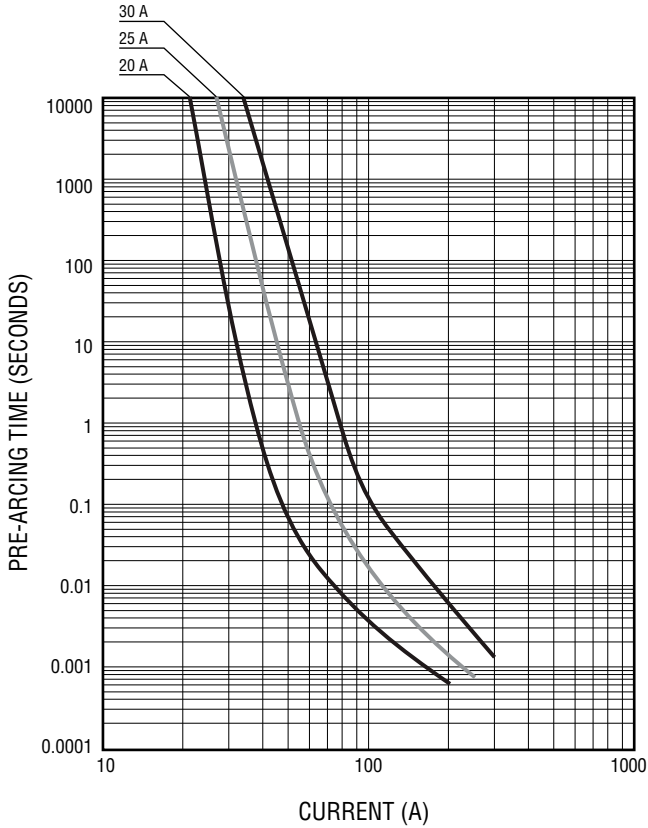
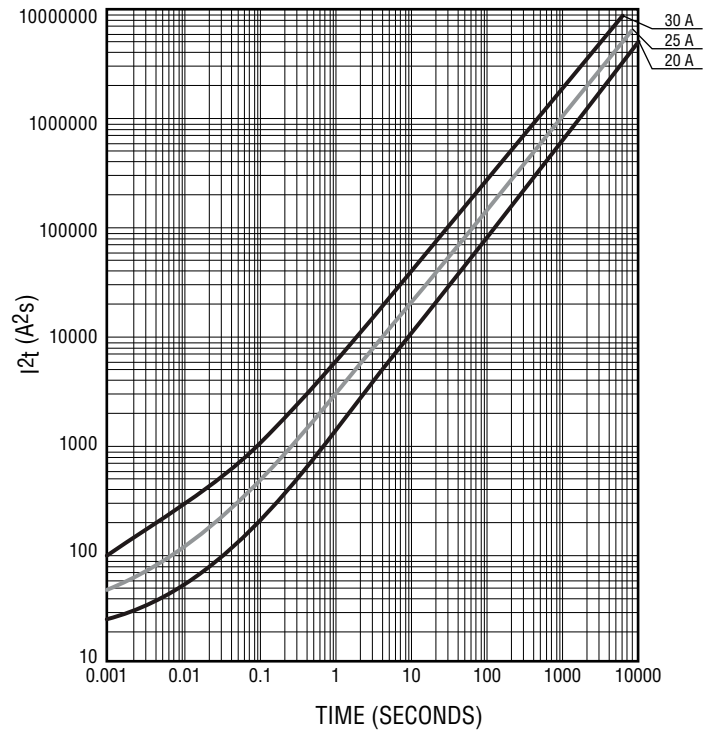


Average Pre-Arcing Time vs. Current Curves



Average  $I^2t$  vs.  $t$  Curves

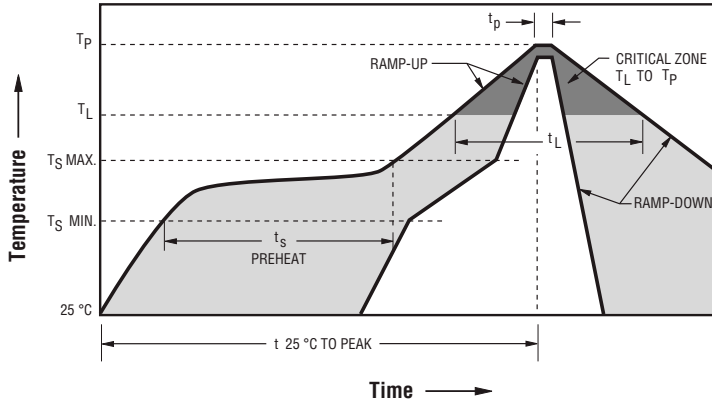


Specifications are subject to change without notice.

Users should verify actual device performance in their specific applications.

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**Solder Reflow Recommendations**

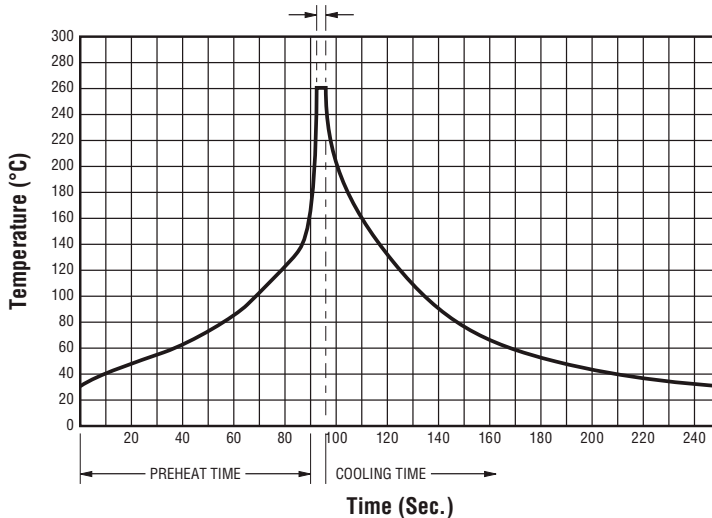


Profile Feature	Pb-Free Assembly
Preheat / Soak: Temperature Min. ( $T_{smin}$ ) Temperature Max. ( $T_{smax}$ ) Time ( $t_s$ ) from ( $T_{smin}$ to $T_{smax}$ )	150 °C 200 °C 60~180 seconds
Ramp Up Rate ( $T_L$ to $T_p$ )	3 °C / second max.
Ramp Up Rate ( $T_{smax}$ to $T_L$ )	5 °C / second max.
Liquidous Temperature ( $T_L$ ) Time ( $t_L$ ) maintained above $T_L$	217 °C 60~150 seconds
Peak Package Body Temperature ( $T_p$ )	260 °C +0/-5 °C
Time within 5 °C of actual peak temperature ( $T_p$ )	10~30 seconds*
Ramp Down Rate ( $T_p$ to $T_L$ )	6 °C / second max.
Time 25 °C to Peak Temperature	8 minutes max.
Do not exceed	260 °C

\* Tolerance for peak profile temperature ( $T_p$ ) is defined as a supplier minimum and a user maximum.

**Solder Wave Recommendations**

Peak Temperature (Dwell Time)



Profile Feature	Pb-Free Assembly
Preheat: Temperature Max. ( $T_{smax}$ ) Time (Min. to Max.)	150 °C 60~90 seconds
Solder Pot Temperature	260 °C max.
Solder Dwell Time	2~3 seconds

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